



## NEWS RELEASE

### FLEX LOGIX WINS TSMC OPEN INNOVATION PLATFORM PARTNER OF THE YEAR AWARD 2017

Mountain View, Calif., September 14, 2017 – [Flex Logix™ Technologies, Inc.](#), the leading supplier of embedded FPGA IP and software, today announced it has won the TSMC Open Innovation Platform's Partner of the Year Award 2017 in the category of New IP for its EFLX® Embedded FPGA IP product.

"We are honored to win this prestigious award as it highlights the close alignment with TSMC that Flex Logix has achieved with its EFLX platform: EFLX embedded FPGA is available for TSMC 40nm, 28nm and 16nm process nodes with array sizes from 100 to >100K LUTs with options for DSP and any size/type of embedded RAM," said Geoff Tate, CEO and co-founder of Flex Logix. "Flex Logix has worked closely with TSMC since the company was founded in 2014 and is proud to meet TSMC's rigorous standards as an IP Alliance Member."

Embedded FPGA is a new type of semiconductor IP enabling high-volume chip designers to incorporate reconfigurable logic to allow chips to be updated even in-system to adapt to new standards, new protocols, new algorithms and to customize chips for customers faster and more cost effectively than mask changes.

The award was presented during a ceremony at this year's [TSMC Open Innovation Platform Ecosystem Forum](#) on September 13, 2017 in Santa Clara. Tate and Senior Vice President of Engineering Cheng Wang accepted the award on behalf of Flex Logix.

#### **About the TSMC Open Innovation Platform®**

The TSMC Open Innovation Platform® hastens the pace of innovation amongst the semiconductor design community, its ecosystem partners and TSMC's IP, design implementation and design for manufacturing (DFM) capabilities, process technology and backend services. A key element of the Open Innovation Platform® is a set of ecosystem alliances and collaborative components initiated and supported by TSMC that more efficiently empower innovation throughout the supply chain and that drive the creation and sharing of newly-created revenue and profits.

#### **About the TSMC Open Innovation Platform (OIP) Ecosystem Forum**

The TSMC OIP Ecosystem Forum brings together TSMC's design ecosystem companies and their customers to share practical, tested solutions to today's design challenges. The event is highlighted by success stories that illustrate best practices from TSMC's design ecosystem. The

forum is a day-long conference kicked-off with trend-setting keynotes and announcements from TSMC and leading IC design company executives and technical sessions are dedicated to selected technical papers from TSMC's EDA, IP, Design Center Alliance and Value Chain Aggregator member companies.

### **About Flex Logix**

Flex Logix, founded in March 2014, provides solutions for reconfigurable RTL in chip and system designs using embedded FPGA IP cores and software. The company's technology platform delivers significant customer benefits by dramatically reducing design and manufacturing risks, accelerating technology roadmaps, and bringing greater flexibility to customers' hardware. Flex Logix has raised more than \$12 million of venture capital. It is headquartered in Mountain View, California and has sales rep offices in China, Europe, Israel, Japan, Taiwan and Texas. More information can be obtained at <http://www.flex-logix.com> or follow on Twitter at @efpga.

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